

BME 398 Design History File

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Joint Department of Biomedical Engineering, UNC-CH and NC State

BME 398 - Biomedical Engineering Design and Manufacturing II

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Traceability Matrix
Unique Identifying Number: TR1
Revision Number: 1
Page Number: 1
Acceptance Status: Accepted

Quality Engineer Signature: *Ben Neill*

Work Breakdown - contribution from each team member

All team members selected and evaluated two user needs and their associated inputs, outputs, verification, and validation. The team also came together to discuss key standards and how they applied to some of our user needs. With 10 total user needs, each group member contributed 20% to the total work.

| User Needs | Design Inputs | Design Outputs | Design Verification | Design Validation | |
|---------------------------------|---|--|---|--|---|
| Temperature Safe Ablation Tip | Temperature of the ablation tip shall not exceed 44 degrees Celsius | Temperature sensor Circuit Diagram [2] | Temperature Calibration Test Multism Simulation [1] | Feedback about temperature monitoring from surgeons, Beta Testing | |
| Sterility | Sterility Assurance Level of at least 10 ⁻⁶ | Ethylene Oxide Sterilization Sterile Packaging Packaging Temperature | Chemical Indicator Sterilization Test Seal Testing Temperature Indicator on Package | User feedback on temperature needed to store, Ethylene Oxide Fluid Dynamic Modeling | ANSI/AAMI ST67:2003. Sterilization of health care products – Requirements for products labeled “STERILE.” This standard requires an SAL value of 10 ⁻⁶ (design input) for products that are intended to come into contact with breached skin or compromised tissue or invasive products that enter normally sterile tissue. |
| Efficiency | Must operate between 915 MHz and 2450 MHz | Circuit Design [2] | Multism Simulation [1] Electromagnetic Simulation | Ablation time of less than 10 minutes, average of 5 minutes in an ex-vivo study, or in an in-vitro clinical trial | |
| Variability in Power | Must be able to deliver 1-100 Watts, dependent on user input. Must have a method for User input (dial, touchscreen, etc.) | Power Supply Datasheet Circuit Design [2] Solidworks part for user control [3] | Benchtop Testing Multism Simulation [1] Assembly Verification | Test effective ablation on various tumor sizes in-vitro or ex-vivo | |
| Biocompatibility | Contact between cells and probe shall have >95% cell viability | Materials data sheet for chosen biocompatible metal/polymers [4] Materials data sheet [4] | Chemical Testing MTT assay Weight Testing | In vivo testing proves no adverse immune responses | |
| Usability | Probe shall weigh less than 2 lbs | Solidworks Schematic of Probe [3] | Statistical testing with weights of probes of different materials | Test that the probe can be lifted and maneuvered easily by physicians; ask for user feedback from physicians | |
| Shelf Stable | Probes shall have a shelf life of 4 years from the date of sterilization | Dupont Tyvek Lid Specifications Materials data sheet [4] | Seal Testing Material Compatibility Testing | Accelerated aging testing (shelf life testing), package strength testing, and package integrity testing according to ISO 11607 | ISO 11607-1:2009. Packaging for terminally sterilized medical devices - Part 1: Requirements for materials, sterile barrier systems and packaging systems. This standard outlines material testing methods, packaging systems, and specific requirements to maintain sterility of the device as it is stored until it is ready to be used. These methods and requirements will be used to ensure a shelf life of 4 years (design input) which appears to be the standard shelf life for most thermal ablation probes. |
| Temperature Safe Ablation Shaft | Temperature of shaft should not exceed 41 degrees Celsius | Temperature sensor Saline Cooling System Insulation | Thermal FEA (Transient) Temperature Calibration Test | Ex vivo tests that monitor the temperature of the shaft during ablation for the longest possible ablation duration. | |
| Rigidity | The probe tip should withstand 50N of force with no deformation | Materials data sheet [4] Mechanical Reinforcements | Finite Element Analysis Three Point Bending Test Compression Test | Feedback from physicians who insert probe into patient's tissue with no deformation. | |
| Comfortable | Probe diameter must not exceed 2mm | Solidworks Schematic of Probe [3] | Assembly Verification | Feedback from patients on any discomfort during and after the procedure due to the diameter | |
| | | | | | |

Risk Register

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Quality Engineer Signature: *Brian Neill*

Work Breakdown - contribution from each team member

Each team member chose two hazards associated with our device and completed their associated harms, probabilities, impacts, risks, and mitigation. With 10 total hazards, each group member contributed 20% to the total work.

| ID | Hazards | Harm | Probability of Occurrence | Impact/Severity | Risk | Acceptable? | Mitigation | Residual Risk |
|----|---|--|---------------------------|-----------------|-----------------|-------------|---|--|
| 1 | Leakage Current out of Handle | User macro/microshock | Likely | High | High Risk (3) | No | Engineering Control: extend insulator to close gap in the handle. PPE: Latex gloves offer high electrical insulation between the leakage current and the user | Leakage current escapes extended insulator and PPE to shock user |
| 2 | Sharp point at end of probe | Tears tissue during insertion/extraction | Unlikely | High | Medium Risk (2) | Yes | Administrative Control: provide training and verification checklist with product | Improper usage results in tissue lacerations |
| 3 | Electric Field produced too large | Destroy surrounding tissue | Unlikely | High | Medium Risk (2) | No | Engineering Control: Include a voltage sensor to detect power output and produced electric field. | Sensor also malfunctions |
| 4 | Probe Diameter too Thick | Uncomfortable for Patient | Unlikely | Moderate | Low Risk (1) | Yes | Engineering Control: Include tolerances on engineering drawings; Alter design based on patient feedback | Probe design not efficient for producing required electric field |
| 5 | Misinterpretation of touch screen interface to set ablation power | Destroy surrounding tissue | Unlikely | High | Medium Risk (2) | No | Administrative Control: provide training and verification checklist with product Engineering Control: Create Intuitive UI and power limits | User does not read manual and misuses device |
| 6 | Overheating of Handle | User Burn | Unlikely | Moderate | Low Risk (1) | Yes | Engineering Control: Insulation of probe | Insulation not incorporated on probe properly |
| 7 | Corrosion of metal probe | Inflammation due to metal particles | Unlikely | Moderate | Low Risk (1) | Yes | Engineering Control: add anti corrosive biocompatible coating Administrative Control: train users to store probe properly to evade exposure to environment that could induce corrosion | Coating could decrease efficiency of ablation |
| 8 | Deformation of Shaft after Insertion | Tissue Damage during Probe Removal | Unlikely | Moderate | Low Risk (1) | Yes | Engineering Control: Selectivity of 316L Stainless Steel (High Stiffness) | Deformation caused by imperfections in the material |
| 9 | Contamination of stainless steel probe | Infection | Likely | Moderate | Medium Risk (2) | No | Elimination: Sterilization techniques after manufacturing process and sterile packaging | Contamination after probe is removed from packaging. |
| 10 | Detached Moving Thumb Tab | Unable to retract the probe, causing electroporation in unwanted areas | Unlikely | High | Medium Risk (2) | No | Engineering Control: Include sensor to track probe extension compared to thumb tab location. | Sensor also malfunctions |

Design Outputs

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Acceptance Status: Accepted

Quality Engineer Signature: *Ben Neill*

Work Breakdown - contribution from each team member

Alex and Drew completed the Bill of Materials, Data Sheet, and PCB, providing 20% of work each.

Mattie and Bevin completed the Engineering Drawings and the Manufacturing Summary, providing 20% of work each.

Jefferson completed the CNC Milling of the probe tip, providing 20% of work.

Manufacturing Summary

In order to fulfill the user need of “Variability in Power,” the nanosecond pulse electric field ablation system must be able to deliver 1-100 Watts of power which can be varied depending on the size of the specific osteoid osteoma that is being removed. The parts of the design that need to be manufactured to verify this need are the subnanosecond pulse generator and the probe. The subnanosecond pulse generator will be built using a circuit outlined in a paper by Krishnaswamy et al. which will make it reasonably easy to assemble [1]. Since this circuit design may need to be modified to meet the needs of our device, it was decided that the generator should be built rather than bought to ensure that we have a solid understanding of the circuit design. This way, we can exchange the circuit elements with confidence that the circuit will still work. The probe will also be built rather than bought since the probe is essentially a long piece of conductive material that can be easily manufactured using CNC milling which can be accomplished in the Fab Lab. This will be financially advantageous since we will only have to buy the raw materials instead of buying the entire part from an outside supplier.

The connectors to the PCB will utilize the poka yoke DFM principle so that they will not be confused. Additionally, all the components are on one side, allowing for easier scaling in manufacturing. The components are orientated in the same direction, allowing for the PCB to be produced using wave soldering. The probe design incorporates many DFM principles including the use of available manufacturing techniques, compatible materials, and optimal geometry. As aforementioned, the probe will be manufactured using CNC milling which can be accomplished using the machine in the Fab Lab or other instrument shops on campus. It will also be composed of 316 Stainless Steel which is low cost and can be CNC milled. The probe will also be quite easy to manufacture since it has a very simple and symmetrical geometry that is essentially a long cylinder with a point.

A printed circuit board (PCB) design will be chosen for the manufacturing technique for the subnanosecond generator because it is a compact solution that can be created in a short amount of time at a low cost. Since the circuit for the generator contains numerous circuit elements, the PCB will allow us to avoid “wire spaghetti” and ensure the circuit is connected properly in a neat and organized manner. CNC milling will be chosen as the manufacturing method for the probe. As previously mentioned, the probe is composed of stainless steel which is compatible with CNC milling. The probe also has a simple geometry that can easily be produced by grinding the ends of a stainless steel cylinder into a point. We also have access to a CNC milling machine through the Fab Lab and other facilities on campus which makes it an ideal manufacturing method.

Bill of Materials

| Part Name | Unique Identifying Number | Description | Quantity | Material | Vendor | Unit Cost | Total Cost |
|----------------------|---------------------------|----------------------|----------|----------|-----------------|-----------|------------|
| Avalanche Transistor | TR1 | Avalanche Transistor | 8 | n/a | Mouser | \$9.73 | \$77.84 |
| DC-DC Converter | CONV1 | DC-DC Converter | 1 | n/a | PicoElectronics | \$136.24 | \$136.24 |
| Resistors (1K) | R1 | Resistors (1K) | 8 | n/a | Mouser | \$1.25 | \$10.00 |
| Resistors (8) | R2 | Resistors (8) | 4 | n/a | Mouser | \$0.46 | \$1.84 |
| Resistors (181K) | R3 | Resistors (181K) | 1 | n/a | Mouser | \$0.10 | \$0.10 |
| Resistors (50) | R4 | Resistors (50) | 1 | n/a | Mouser | \$1.62 | \$1.62 |
| Resistors (8.5k) | R5 | Resistors (8.5k) | 1 | n/a | Mouser | \$0.10 | \$0.10 |
| Resistors (255) | R6 | Resistors (255) | 1 | n/a | Mouser | \$0.10 | \$0.10 |
| Resistors (105) | R7 | Resistors (105) | 1 | n/a | Mouser | \$0.10 | \$0.10 |
| Capacitor (120p) | C1 | Capacitor (120p) | 1 | n/a | Digikey | \$21.32 | \$21.32 |
| Capacitor (18p) | C2 | Capacitor (18p) | 1 | n/a | Digikey | \$14.34 | \$14.34 |
| Capacitor (6.8p) | C3 | Capacitor (6.8p) | 2 | n/a | Digikey | \$14.34 | \$28.68 |
| Capacitor (3.3p) | C4 | Capacitor (3.3p) | 1 | n/a | Digikey | \$15.50 | \$15.50 |
| Capacitor (2.2p) | C5 | Capacitor (2.2p) | 1 | n/a | Digikey | \$1.50 | \$1.50 |
| Capacitor (1.5p) | C6 | Capacitor (1.5p) | 1 | n/a | Digikey | \$1.50 | \$1.50 |
| Capacitor (1.0p) | C7 | Capacitor (1.0p) | 1 | n/a | Digikey | \$1.50 | \$1.50 |
| Capacitor (0.8p) | C8 | Capacitor (0.8p) | 1 | n/a | Digikey | \$0.80 | \$0.80 |
| Capacitor (12p) | C9 | Capacitor (12p) | 1 | n/a | Digikey | \$14.34 | \$14.34 |

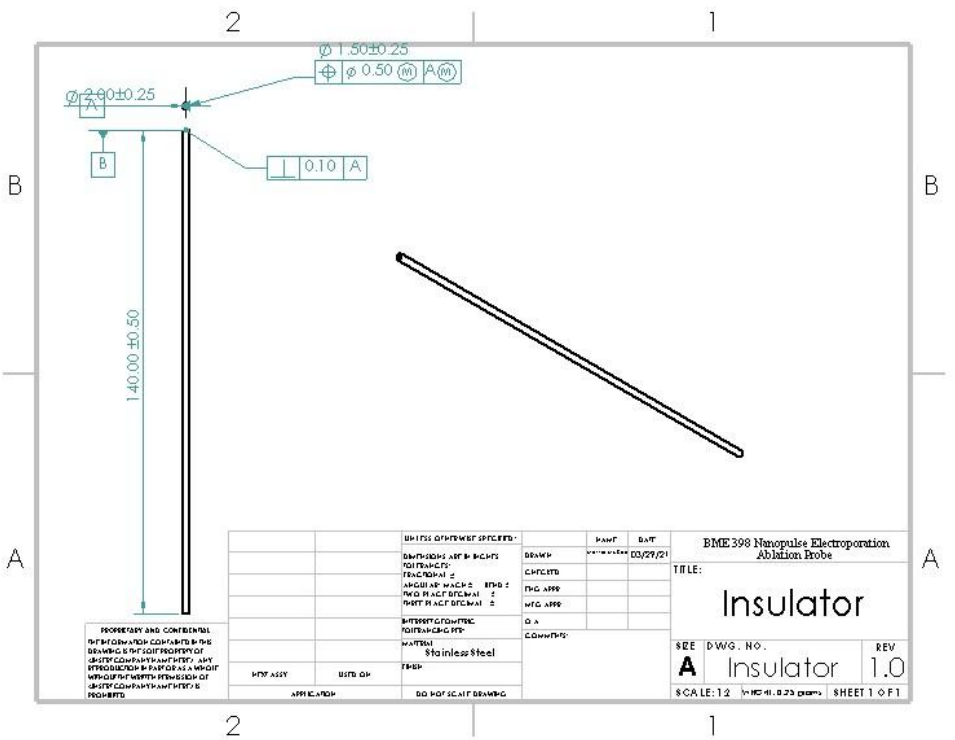
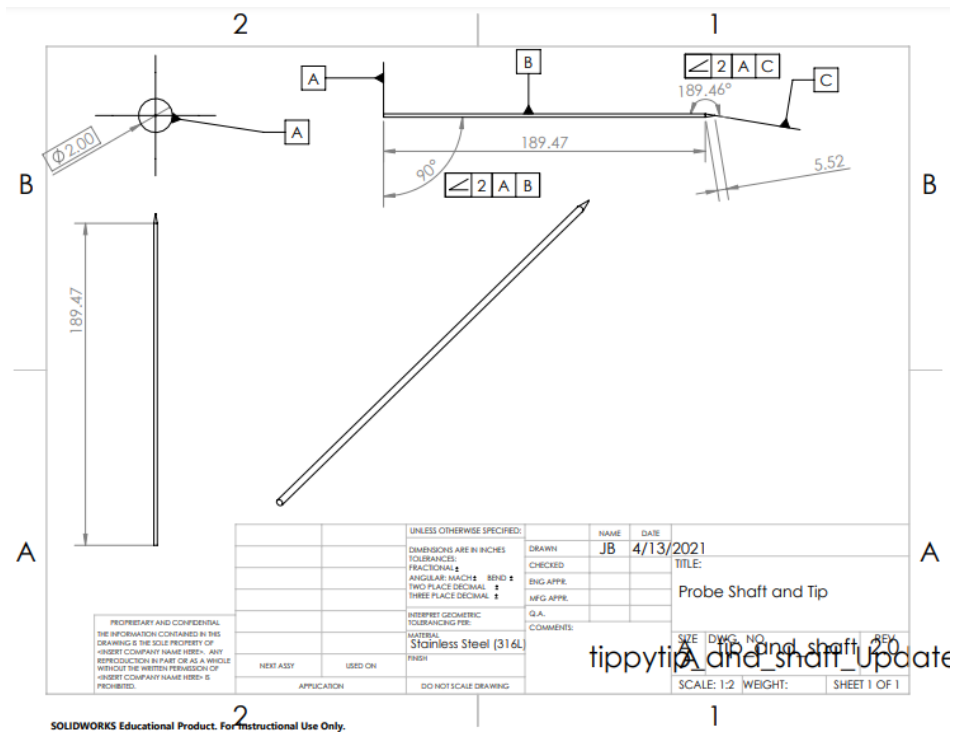
| | | | | | | | |
|-----------------------|------|--|---|----------------------|----------|---------|---------|
| Capacitor (0.1u) | C10 | Capacitor (0.1u) | 1 | n/a | Sparkfun | \$0.95 | \$0.95 |
| Capacitor (10n/0.01u) | C11 | Capacitor (10n/0.01u) | 1 | n/a | Sparkfun | \$0.95 | \$0.95 |
| Zener Diode (300 V) | D1 | Zener Diode (300 V) | 6 | n/a | Mouser | \$12.67 | \$76.02 |
| Zener Diode (270 V) | D2 | Zener Diode (270 V) | 2 | n/a | Mouser | \$0.30 | \$0.60 |
| SMA Connector | J1 | SMA Connector | 1 | n/a | Mouser | \$3.07 | \$3.07 |
| Transformer | T1 | Transformer | 1 | n/a | Digikey | \$3.92 | \$3.92 |
| PCB | PCB1 | Printed Circuit Board | 1 | n/a | JLCPCB | \$7.40 | \$7.40 |
| Metal Probe | PRB1 | 316L Stainless Steel Rods Wire Diameter 2mm, length 0.5m | 1 | 316L Stainless Steel | Ethionec | \$6.99 | \$6.99 |

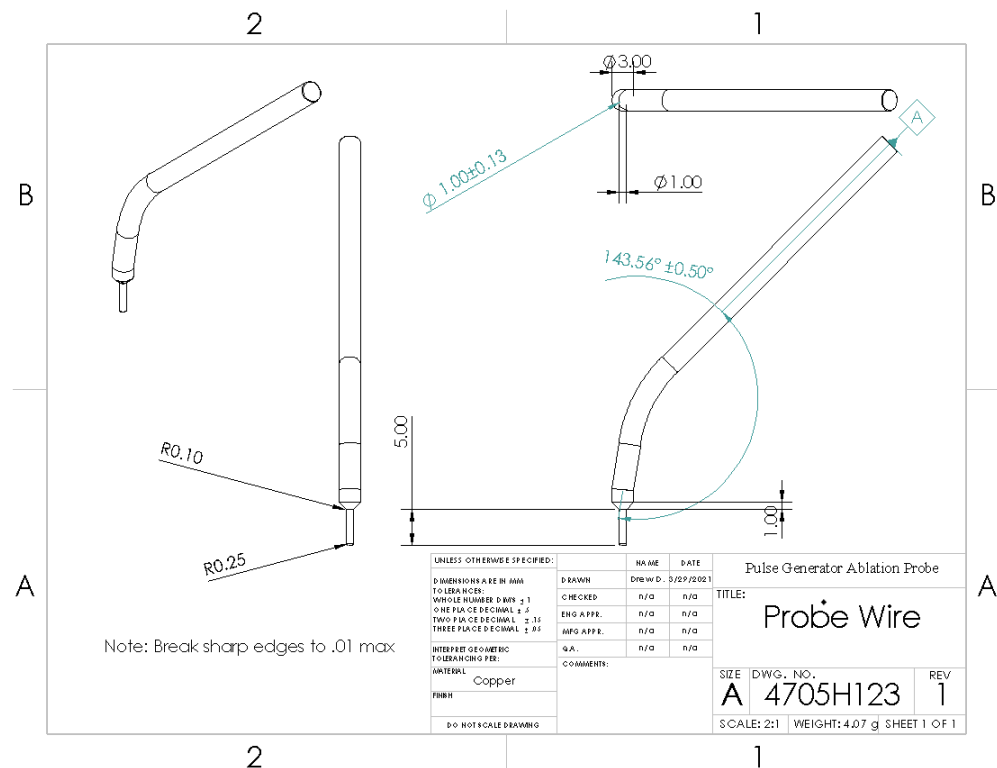
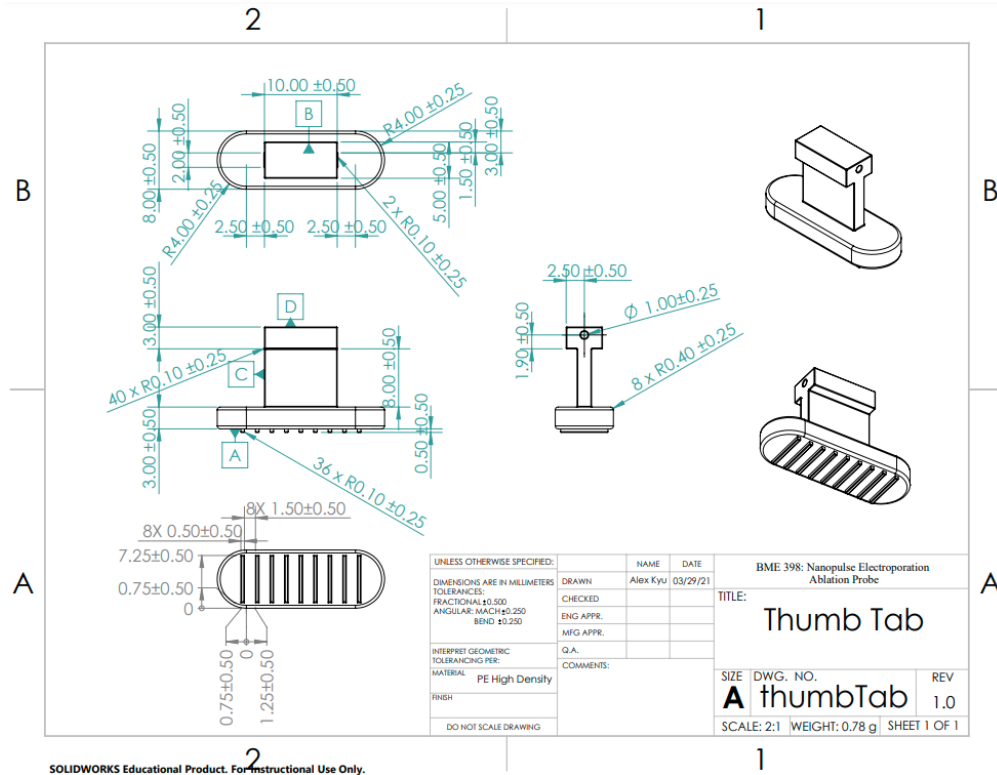
Total Prototyping Cost (Probe and Generator): \$427.32

Data Sheet or MDS

| Part Name | Unique Identifying Number | Datasheet |
|----------------------|---------------------------|---|
| Avalanche Transistor | TR1 | https://www.mouser.com/datasheet/2/115/FMMT415-46058.pdf |
| DC-DC Converter | CONV1 | https://www.picoelectronics.com/node/13287 |
| Zener Diode (300 V) | D1 | https://www.mouser.com/datasheet/2/268/SA5_37-1592261.pdf |
| Zener Diode (270 V) | D2 | https://www.mouser.com/datasheet/2/308/MM5Z4678T1_D-1811647.pdf |
| Transformer | T1 | https://media.digikey.com/pdf/Data%20Sheets/Pulse%20PDFs/LAN%20Isolation%20Transformer%20Catalog.pdf |
| Metal Probe | PRB1 | https://www.metalshims.com/t-316-Stainless-Steel-technical-data-sheet.aspx |

Engineering Drawings





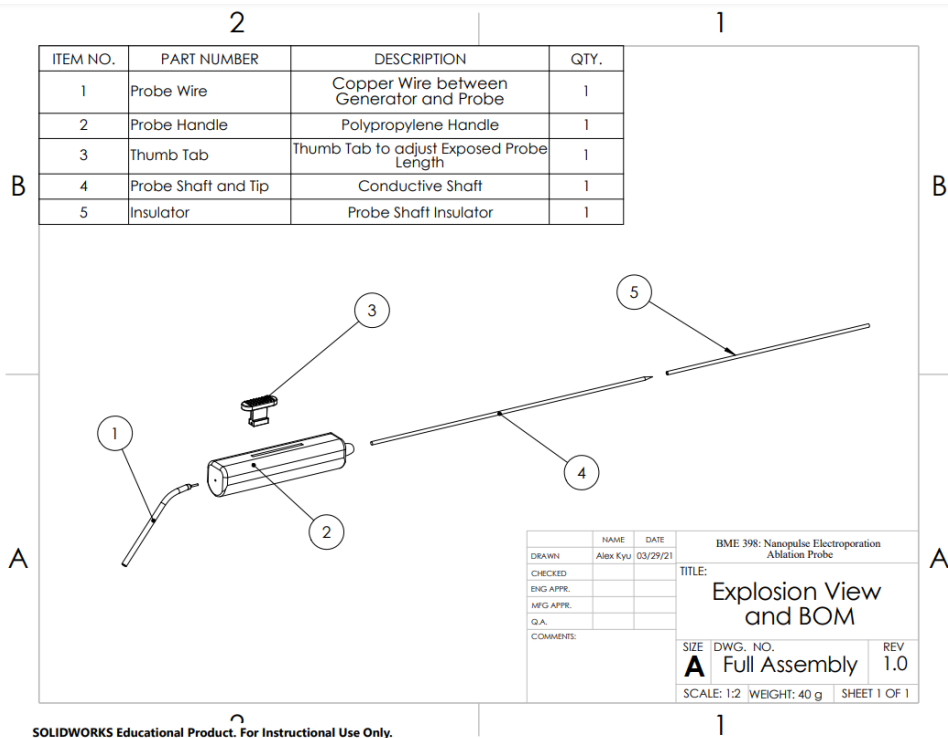
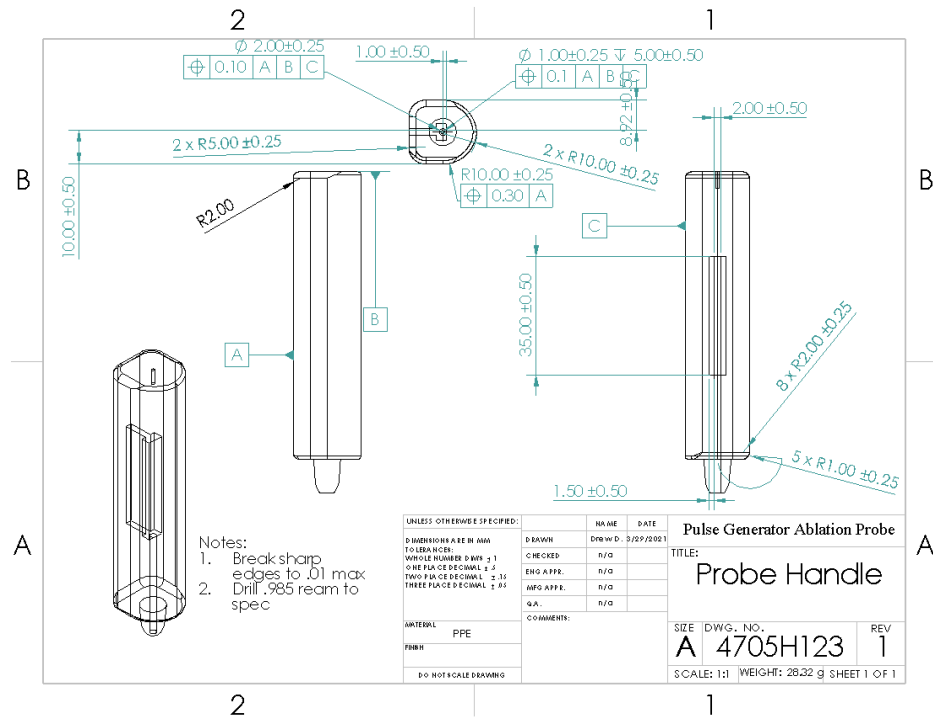


Figure 1: Engineering drawings for each part of the ablation probe created in Solidworks

CNC Milling: Probe Tip

Tool Crib:

| | |
|--------------------------|---------------------|
| Main Removal of Material | T01 - 6mm Flat End |
| Shaping Probe Tip | T07 - 4mm Ball Nose |

Results:

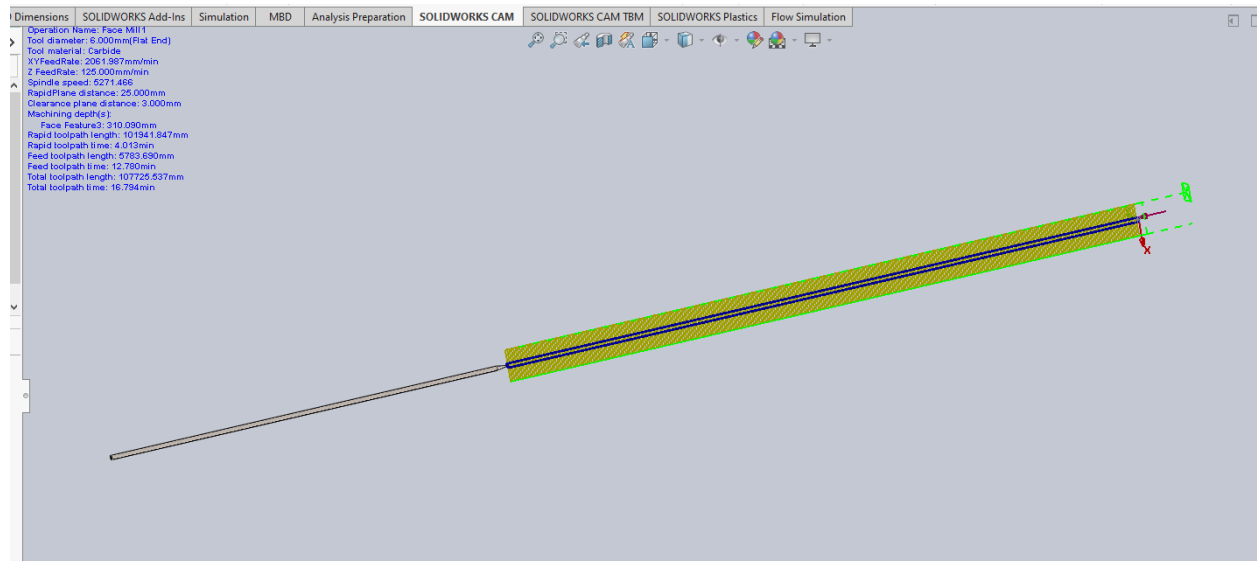


Figure 2: the CNC milled tip of the ablation probe

G-code: see attached

Pulse Generator PCB

See attached schematic, board and gerber files.

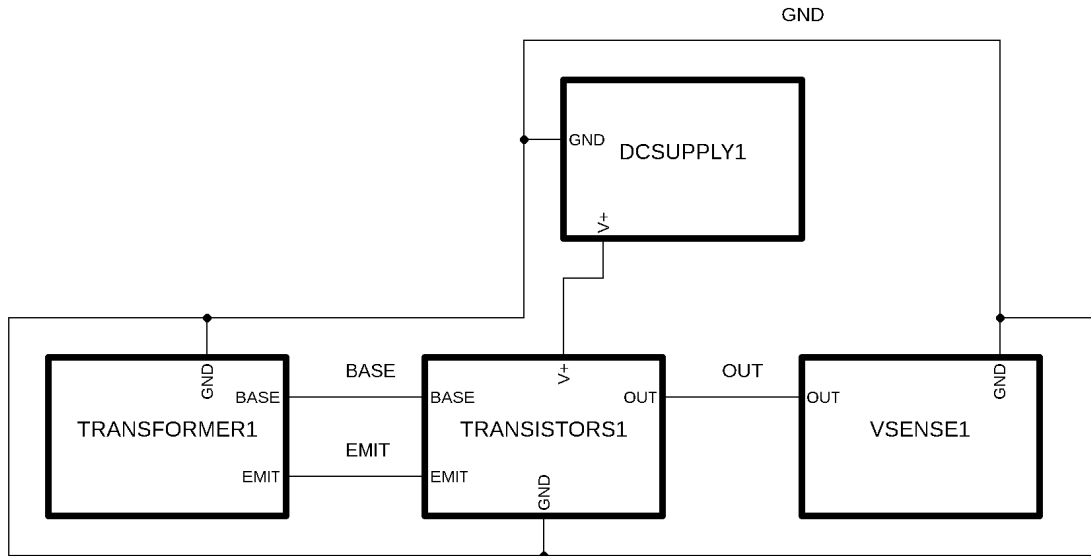


Figure 3: the outline schematic of the PCB

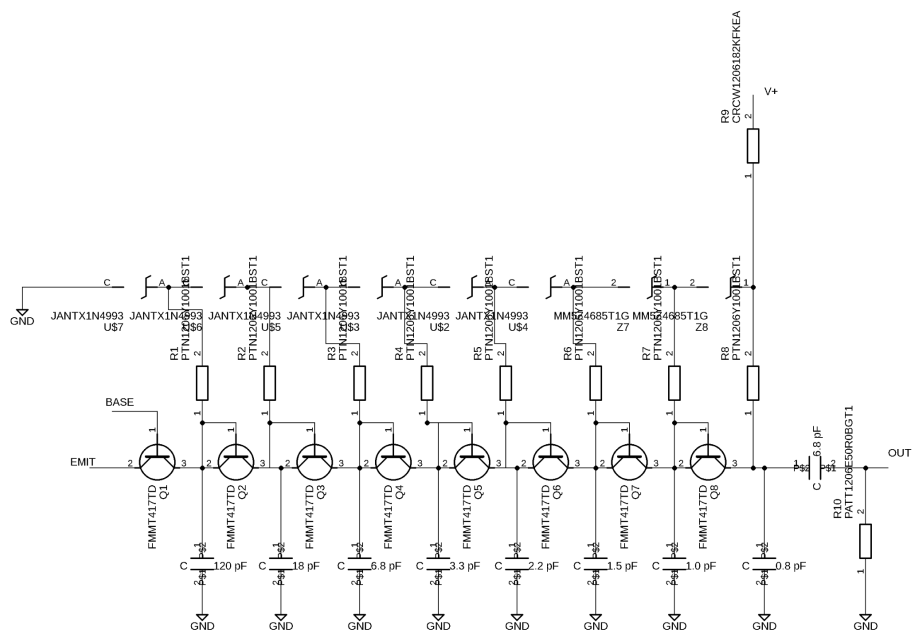


Figure 4: the transistors schematic block

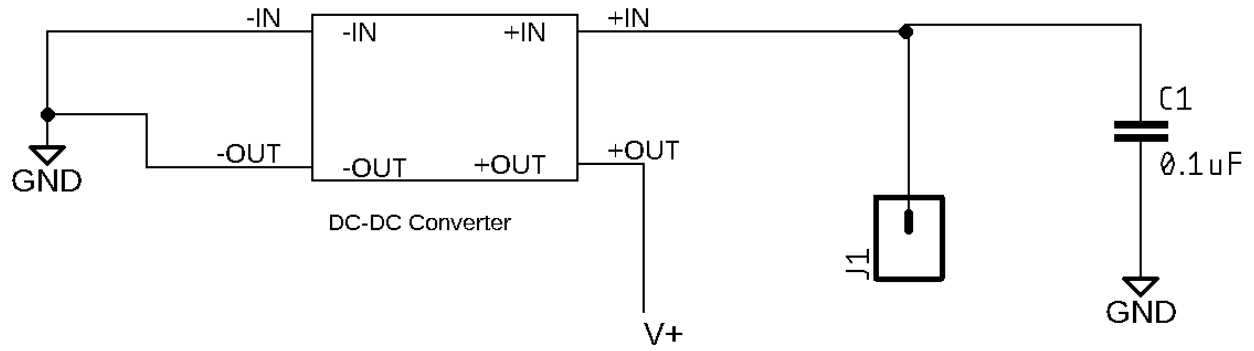


Figure 5: the DC supply schematic block is shown including the DC-DC converter

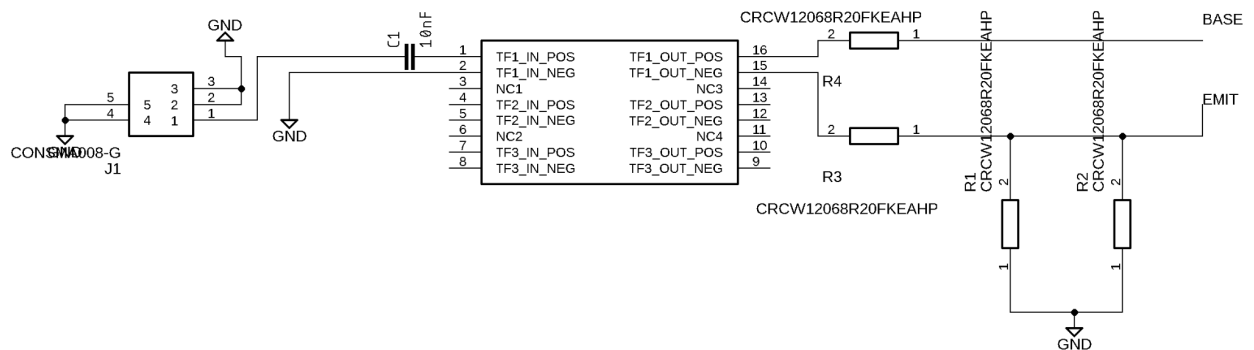


Figure 6: the transformer schematic block is shown including a connector for the trigger source and the transformer used

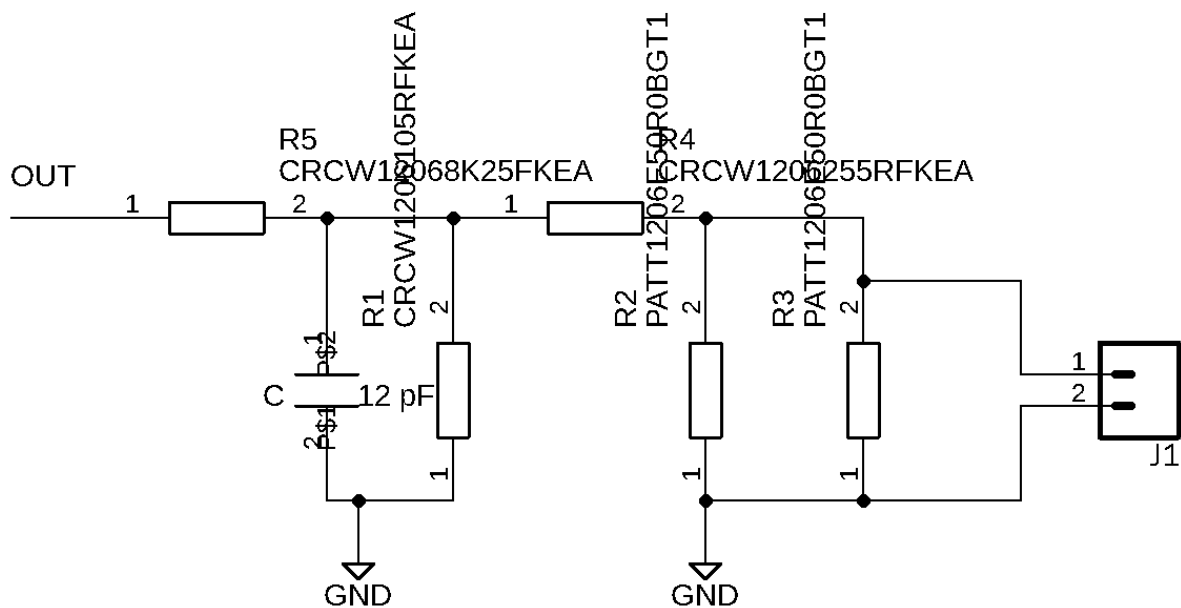


Figure 7: the voltage sensor schematic block

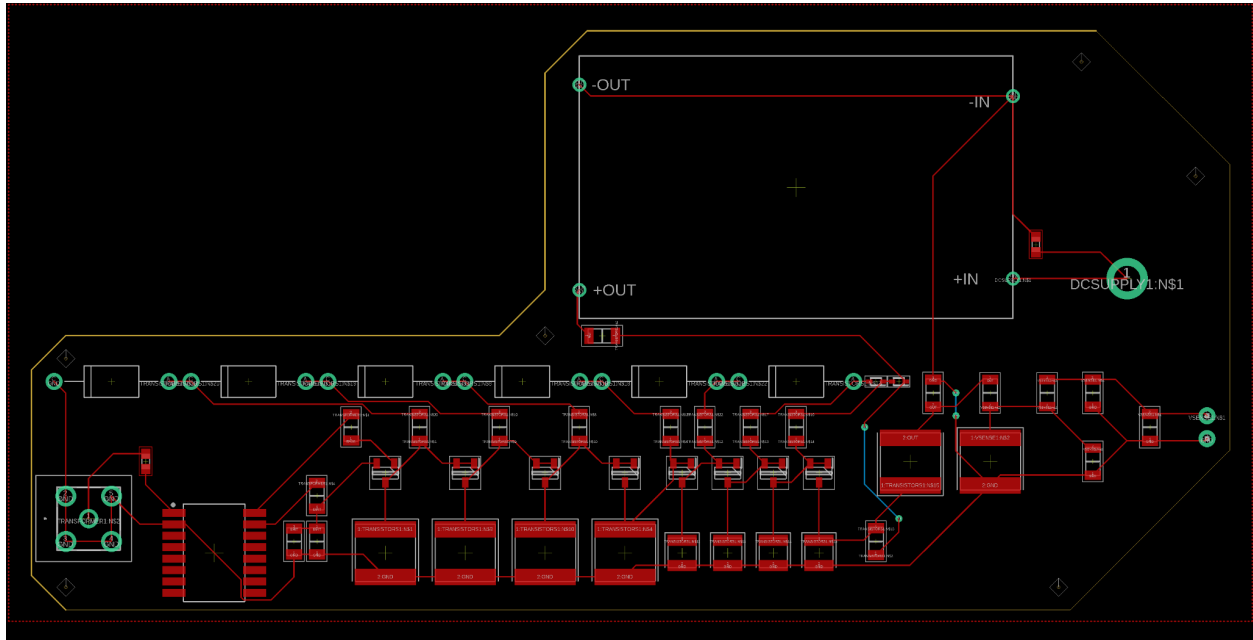


Figure 8: the PCB board file highlighting the placement of each part

Verification/Validation
Unique Identifying Number: VV1
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Quality Engineer Signature: *Bevin Neill*

Work Breakdown - contribution from each team member

Alex and Drew designed the circuit in Multisim and calculated results from the simulation, providing 50% of work each.

Bevin, Jeff and Mattie worked on the final paper deliverable while Alex and Drew completed the verification/validation document.

Verification/Validation

Using Multisim software, the nanosecond pulse generator circuit was modeled as shown in figure 1 and simulated with a transient response of time step 0.1 ns. The waveform produced was analyzed and the peak voltage and rise time of the output waves were recorded. This analysis was performed for varying voltage peaks of the trigger source input to the circuit while keeping a constant rise time of 0.5 ns. While spice code for avalanche transistors was downloaded, use of the code for the transistor component did not yield a pulse wave. Accordingly, the bipolar junction transistor (BJT) NPN transistor was used to model the avalanche transistor. This transistor provided a conservative estimate of the circuit as the transistor lacked the quick response of the avalanche transistors. The DC power supply block, which consisted of a 8-14.5 VDC power supply followed by a DC-DC converter, was simplified as a 2.5 kV voltage source in the simulation. The transformer was modeled with no leakage inductance or resistance; the core was modeled as non-ideal with a flux of $250\mu\text{Wb} * \tanh(.2*i)$ where “i” was the magnetizing inductance current.

While the results of the simulation didn't meet the desired specifications, it did confirm that the project is plausible. With the use of Avalanche Transistors and the right components, this circuit should be able to produce the desired waveforms. Unfortunately, with the limitations of Multisim and inability to fully model the components, these waveforms could not be reproduced at the magnitude required for our device, despite simplifying the circuit to only two transistor stages. The results shown below are from the circuit schematic with all eight transistor stages (Figure 1).

However, a desired waveform was generated using switches instead of transistors, demonstrating that given a working model of the desired Avalanche Transistor, this simulation should produce the correct output voltage. Furthermore, other components may have an influence in the results too. Results for varying trigger source voltages are shown below, demonstrating that higher trigger source voltages, decreased rise time and increased peak pulse voltages (Figure 2, 3). The simulation for the pulse with a 5V trigger source is also shown below. A relatively low rise time of 5.5352 nanoseconds is shown, which could be further improved by the use of Avalanche transistors which have subnanosecond rise times (Figure 4).

Table 1: Multisim Parameters

| Parameters | Value |
|--------------------------------|-------------------------|
| Trigger Source Initial Value | 0 V |
| Trigger Source Pulse Value | 5 V |
| Trigger Source Rise Time | 0.5 ns |
| Trigger Source Fall Time | 1 ns |
| Trigger Source Pulse Width | 5 us |
| Period | 1 ms |
| Transformer Non-ideal Core | Flux = 250u*tanh(0.2*i) |
| Transformer Leakage Inductance | 0 H |
| Transformer Coil Resistances | 0 Ω |
| Transformer Coil Turns | 4:4 |
| Simulation Type | Transient Analysis |
| Initial Conditions | Set to Zero |
| Maximum Time Step Size | 0.1 ns |
| Initial Time Step Size | 0.1 ns |

Simulation Results:

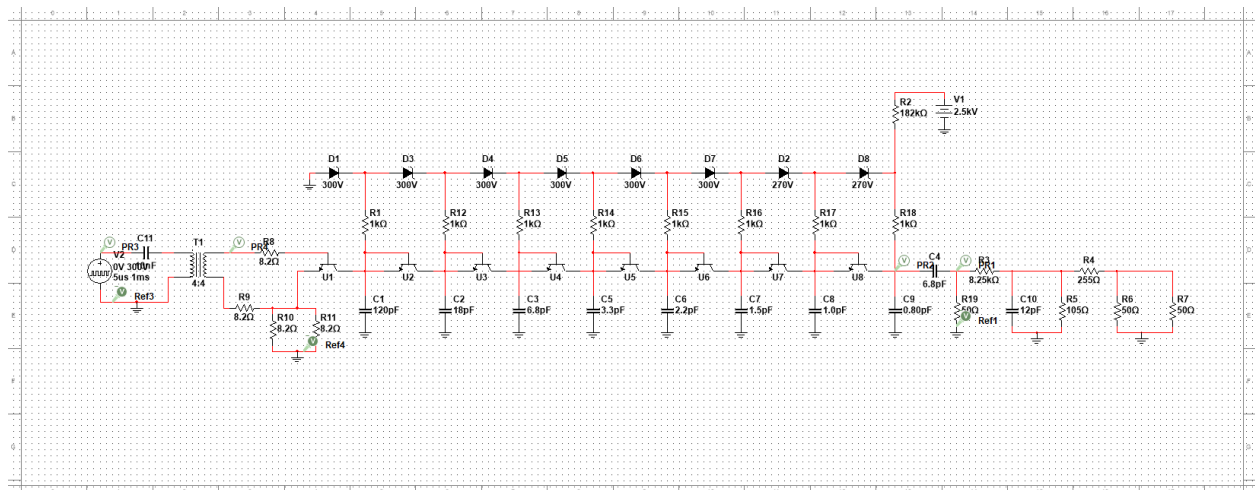


Figure 1: Multisim Circuit Schematic

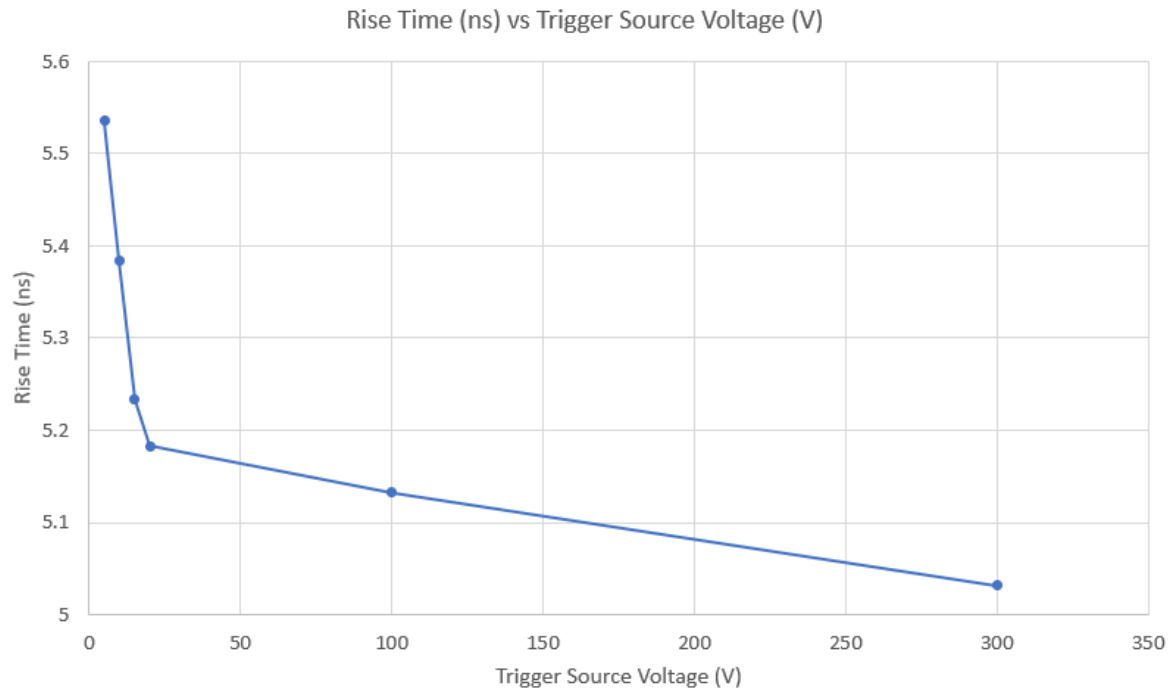


Figure 2: Simulation Results comparing Rise Time of the Pulse with changing Trigger Source Voltages.

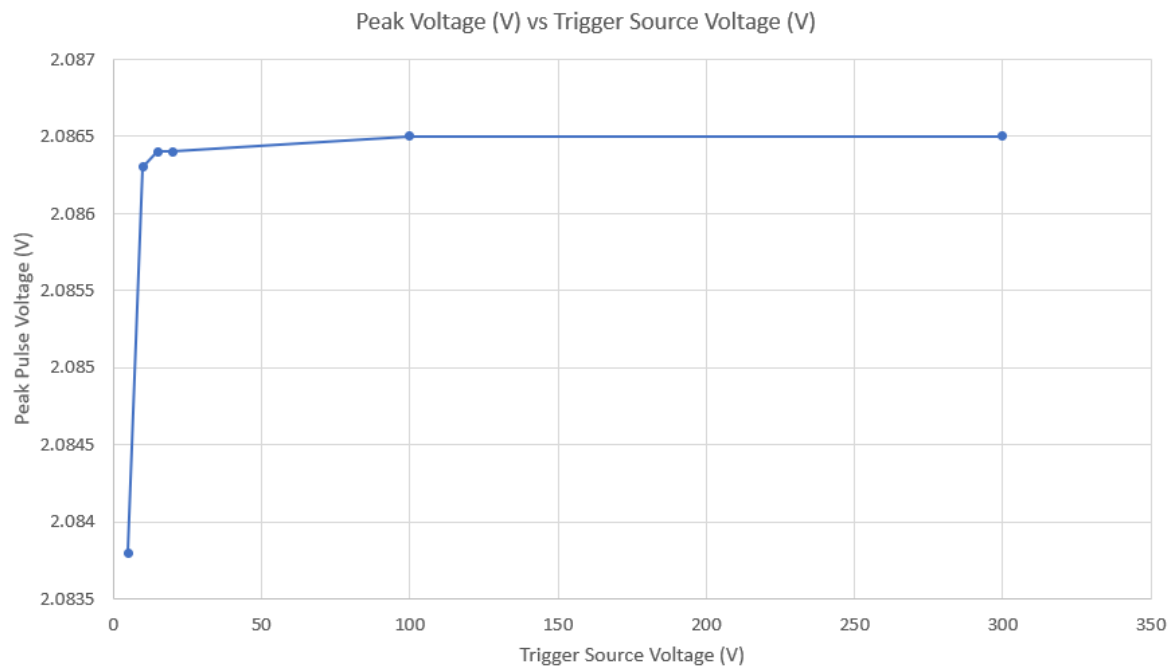


Figure 3: Simulation Results comparing Peak Pulse Voltage with changing Trigger Source Voltages.

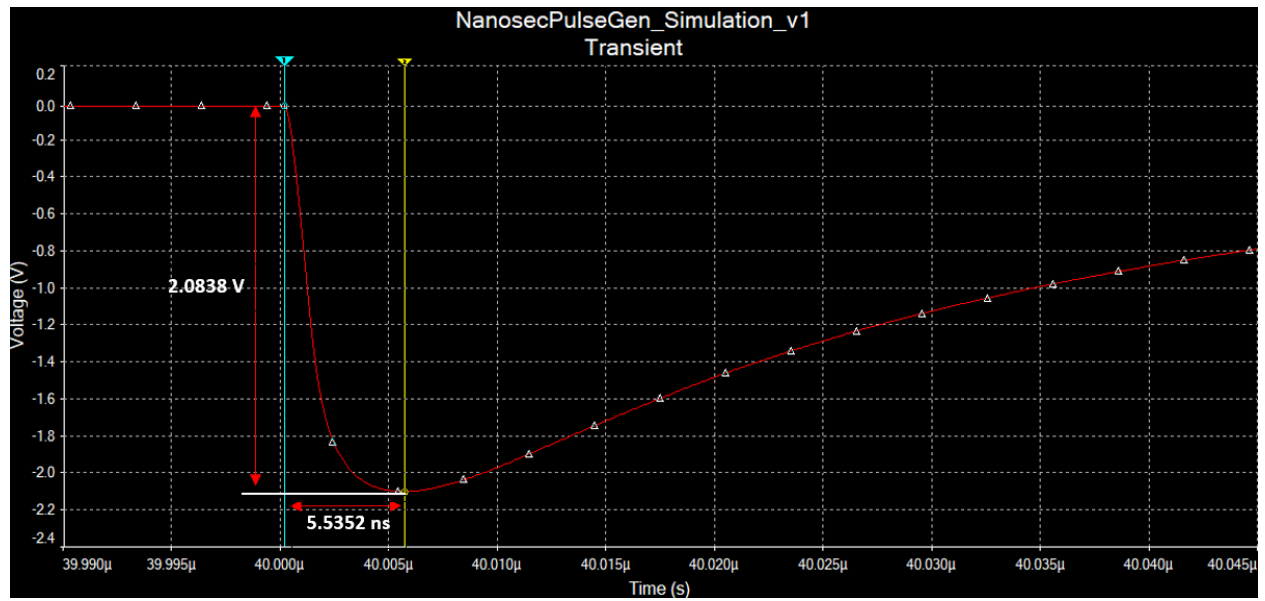


Figure 4: Simulation Results with a 5V Trigger Source. The Rise time was 5.5352 nanoseconds and the Peak Pulse Voltage was 2.0838 V.